

NOTE:

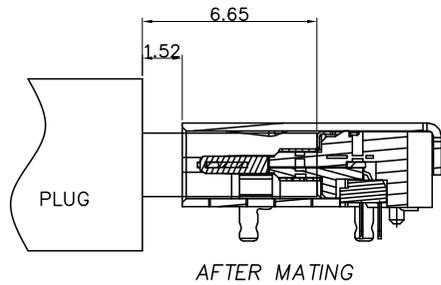
- MATERIAL SPECIFICATION:
  - HOUSING: LCP COLOR SEE TABLE 1, UL94 V-0.
  - CONTACTS: COPPER ALLOY (C1814)
  - MID PLATE & SPRING: STAINLESS STEEL (SUS301)
  - FRONT SHELL & COVER: STAINLESS STEEL (SUS304)
- PLATING SPECIFICATION:
  - CONTACTS:
    - Ni 50u" MIN. UNDER PLATING OVER ALL.
    - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW THE P/N)
    - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
  - FRONT SHELL & COVER:
    - Ni 30u" MIN. UNDER PLATED OVER ALL.
  - MID PLATE & EMI SPRING:
    - CLEAR ONLY
- MECHANICAL PERFORMANCE,
  - INSERTION FORCE: 0.5~2.0kgf.
  - REMOVAL FORCE: 0.8kgf~2.0kgf.
  - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE,
  - CURRENT RATING: 3.0A  
VOLTAGE RATING: 5.0V
  - LLCR:
    - VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
    - SHIELD: 50mΩ/MAX.
    - LLCR MAX. CHANGE OF ALL PINS: 10mΩ
  - INSULATION RESISTANCE: 100MΩ MIN
  - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
- ENVIRONMENTAL PERFORMANCE:
  - OPERATING TEMPERATURE: -25°C~+85°C.
- IR REFLOW:
  - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

TABLE 1

ITEM	P/N	HOUSING COLOR	CONTACTS	
			FUNCTION AREA	SOLDER AREA
1	UCB11-2400M2ANL-H01	BLACK	Au: 3u"	Au: G/F
2	UCB11-2400M5ANL-H02	BLACK	Au: 15u"	Au: G/F
3	UCB11-2400M7ANL-H03	BLACK	Au: 30u"	Au: G/F
4	UCB11-2400M2SNL-H04	NATURAL	Au: 3u"	Au: G/F

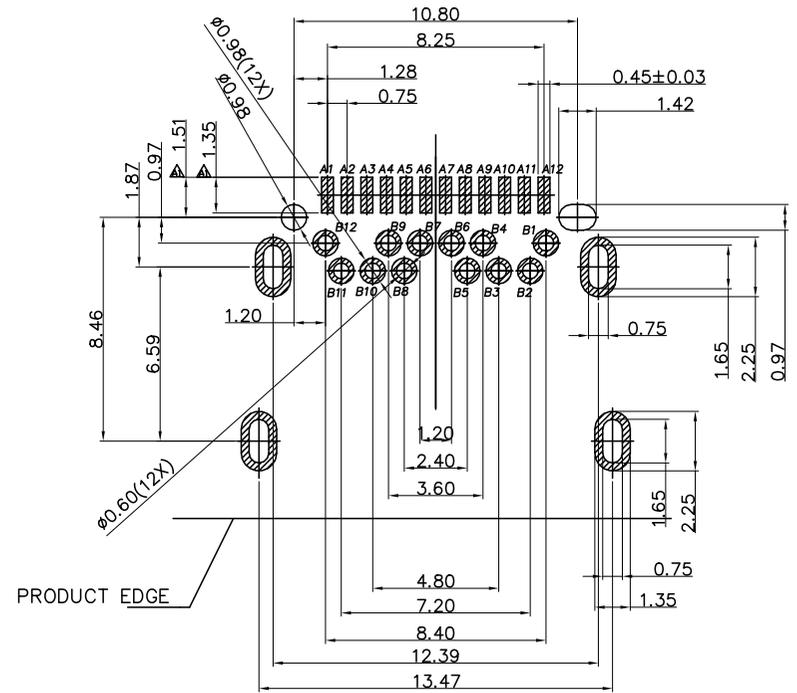
REV.	REVISION RECORD	DATE	UNIT: MM	GENERAL TOLERANCES		SCALE 1:1	NAME	DATE	PART NO.	DWG NO.					
				LINEAR	ANGLES										
A0	NEW RELEASE	2019. 10. 21	mm	0.0±0.20	X° ±2°	APPROVED	SKY	2022. 7. 27	UCB11-2400M2ANL-H01	ENDE05	TITLE	REV	A1	SHEET	1/3
A1	increase bonding pad dimensioning	2022. 7. 27	mm	0.00±0.10	X.X° ±1°	DESIGNER	GSQ	2022. 7. 27							
			mm	0.000±0.05	X.XX° ±0.5°	DRAWN	Xie Liang	2019. 10. 21	USB TYPE C 3.1 24PIN SMT&THT						

HF



USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A2	SSTXp1	B11	SSRXp1
A3	SSTXn1	B10	SSRXn1
A4	Vbus	B9	Vbus
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	Vbus	B4	Vbus
A10	SSRXn2	B3	SSTXn2
A11	SSRXp2	B2	SSTXp2
A12	GND	B1	GND

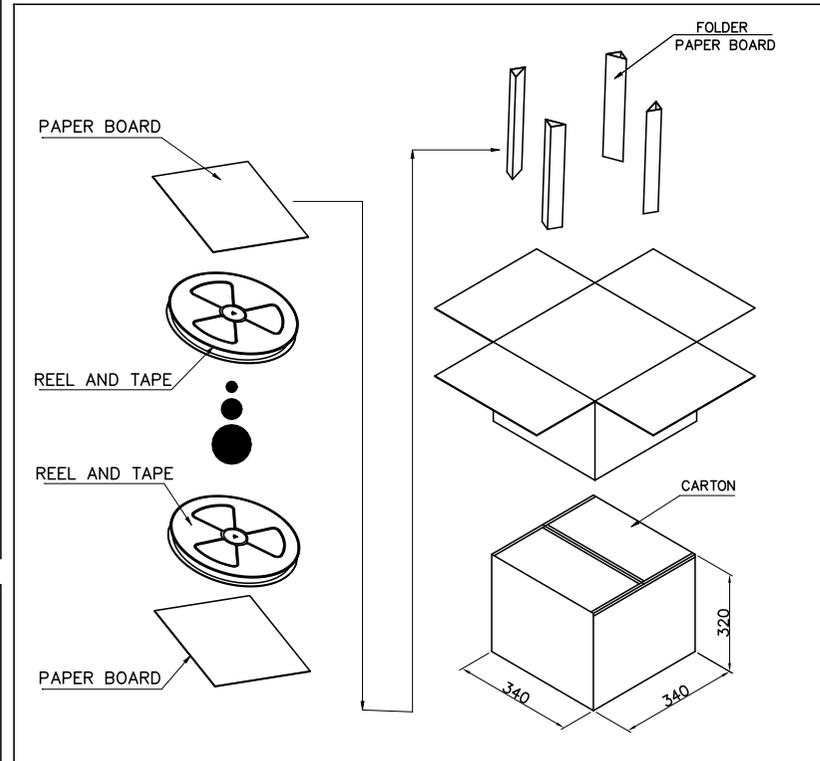
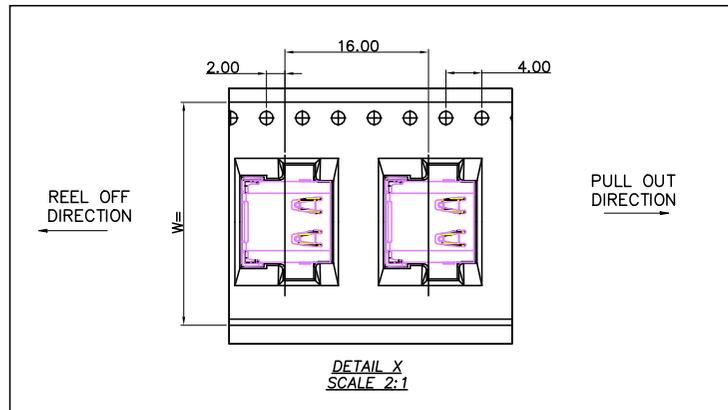
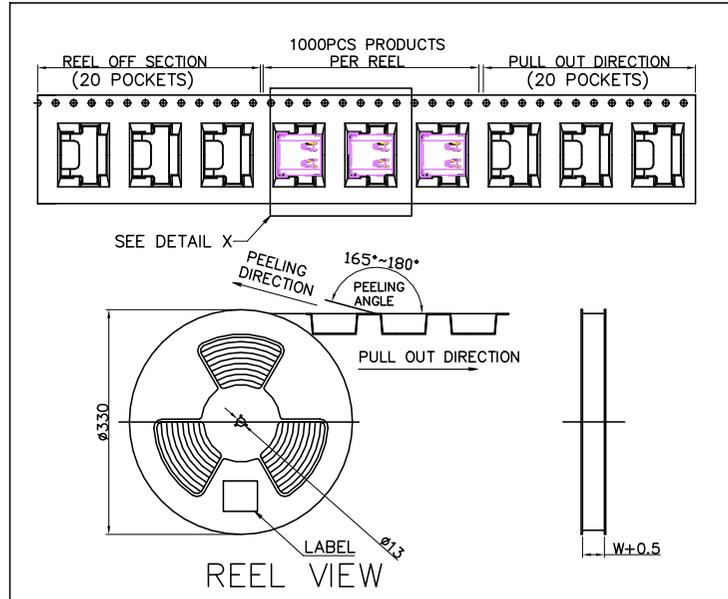


SCALE 1.5:1

RECOMMENDED PCB LAYOUT(TOP VIEW)  
THICKNESS 0.8 MM;DEFAULT TOLERANCE:  $\pm 0.05$

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE 1:1	NAME	DATE	PART NO.	DWG NO.				
A0	NEW RELEASE	2019.10.21		LINEAR	ANGLES	APPROVED	SKY	2022.7.27	UCB11-2400M2ANL-H01	ENDE05				
A1	increase bonding pad dimensioning	2022.7.27	0.0 $\pm$ 0.20	X° $\pm$ 2°	DESIGNER	GSQ	2022.7.27	TITLE						
			UNIT: MM	0.00 $\pm$ 0.10	X.X° $\pm$ 1°			USB TYPE C 3.1 24PIN SMT&THT						
			SIZE: A1	0.000 $\pm$ 0.05	X.XX° $\pm$ 0.5°	DRAWN	Xie Liang	2019.10.21			REV	A1	SHEET	2/3

HF



	REEL/TRAY	CARTON
CONNECTOR (PCS)	1000	10000

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE 1:1	NAME	DATE	PART NO.	DWG NO.		
AO	NEW RELEASE	2019. 10. 21		UNIT: MM	LINER	ANGLES	APPROVED	SKY	2022. 7. 27	UCB11-2400M2ANL-H01		ENDE05
			SIZE: A4	0.00±0.25	X.X° ±1°	DESIGNER	GSQ	2022. 7. 27	TITLE			
				0.000±0.15	X.XX° ±0.5°	DRAWN	Xie Liang	2019. 10. 21	USB TYPE C 3.1 24PIN SMT&THT Packing drawing			
									REV	A0	SHEET	3/3

1

2

3

4

5

6

7

8